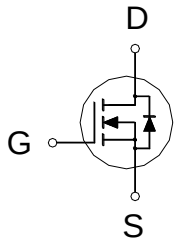
杰力科技股份有限公司
Excelliance MOS Corporation

EMB12N03HR

N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	30V
$R_{DSON\ (MAX.)}$	11.5mΩ
I_D	25A



UIS, Rg 100% Tested

RoHS & Halogen Free & TSCA Compliant

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	T_C = 25 °C	I_D	25	A
	T_C = 100 °C		20	
Pulsed Drain Current[1]		I_{DM}	100	
Avalanche Current		I_{AS}	30	
Avalanche Energy	L = 0.1mH, ID=30A, RG=25Ω	E_{AS}	45	mJ
Repetitive Avalanche Energy[2]	L = 0.05mH	E_{AR}	22.5	
Power Dissipation	T_C = 25 °C	P_D	35	W
	T_C = 100 °C		14	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

100% UIS testing in condition of V_D=30V, L=0.1mH, V_G=10V, I_L=18A, Rated V_{DS}=30V N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		3.5	°C / W
Junction-to-Ambient[3]	$R_{\theta JA}$		62	

[1]Pulse width limited by maximum junction temperature.

[2]Duty cycle < 1%

[3]The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25°C.

[4]Guarantee by Engineering test

ELECTRICAL CHARACTERISTICS (T_C = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1	1.7	3	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 24V, V_{GS} = 0V			1	μA
		V_{DS} = 20V, V_{GS} = 0V, T_J = 125 °C			25	
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} = 5V, V_{GS} = 10V	25			A
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = 10V, I_D = 15A		9.7	11.5	mΩ
		V_{GS} = 4.5V, I_D = 10A		13	16	
Forward Transconductance[1]	g_{fs}	V_{DS} = 5V, I_D = 15A		15		S
DYNAMIC						
Input Capacitance	C_{iss}	V_{GS} = 0V, V_{DS} = 15V, f = 1MHz		1050		pF
Output Capacitance	C_{oss}			141		
Reverse Transfer Capacitance	C_{rss}			87		
Gate Resistance	R_g	V_{GS} = 15mV, V_{DS} = 0V, f = 1MHz		1.2		Ω
Total Gate Charge[1,2]	Q_g(V_{GS}=10V)	V_{DS} = 15V, V_{GS} = 10V, I_D = 15A		17.6		nC
	Q_g(V_{GS}=4.5V)			9.0		
Gate-Source Charge[1,2]	Q_{gs}			2.6		
Gate-Drain Charge[1,2]	Q_{gd}			4.0		
Turn-On Delay Time[1,2]	$t_{d(on)}$	V_{DS} = 15V, I_D = 5A, V_{GS} = 10V, R_G = 3Ω		8		nS
Rise Time[1,2]	t_r			8		
Turn-Off Delay Time[1,2]	$t_{d(off)}$			15		
Fall Time[1,2]	t_f			10		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_C = 25 °C)						
Continuous Current	I_S				25	A
Pulsed Current[3]	I_{SM}				100	
Forward Voltage[1]	V_{SD}	I_F = I_S, V_{GS} = 0V			1.3	V
Reverse Recovery Time	t_{rr}	I_F = I_S, dI_F/dt = 100A / μS		18		nS
Peak Reverse Recovery Current	$I_{RM(REC)}$			100		A
Reverse Recovery Charge	Q_{rr}			10		nC

[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

[3]Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMB12N03HR for EDFN 5 x 6

B12N03R: Device Name

ABCDEFG: Date Code

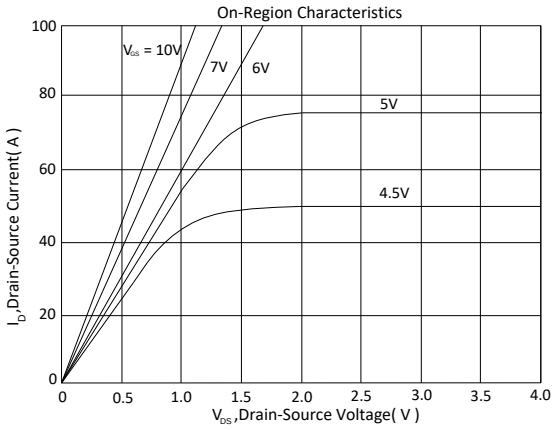
A: Assembly House

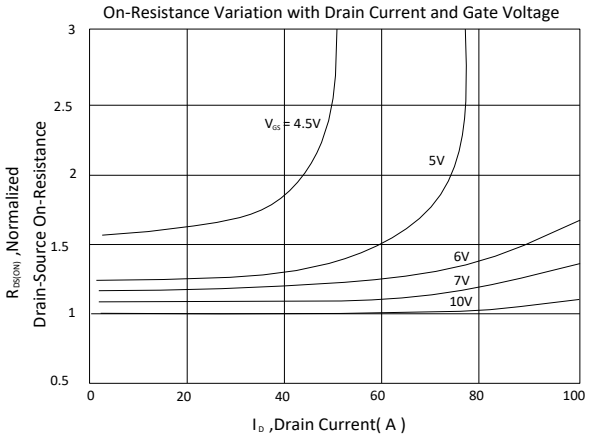
B: Year(A:2008 B:2009 C:2010….)

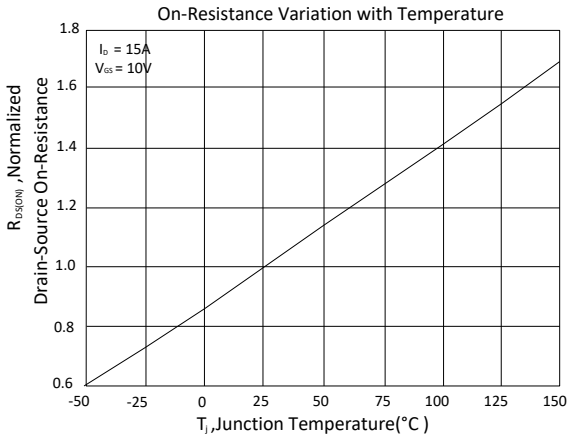
C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)

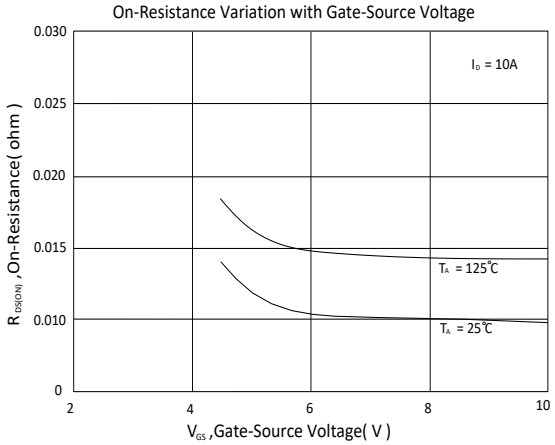
DEFG: Serial No.

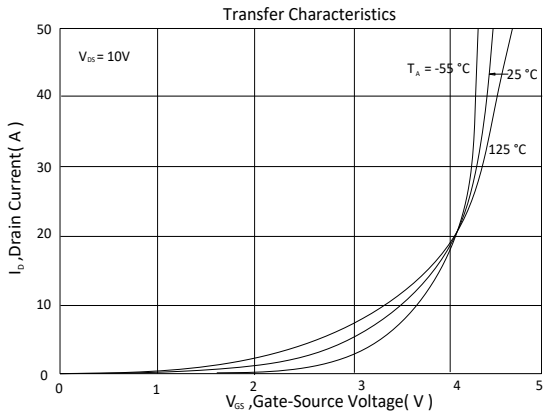
TYPICAL CHARACTERISTICS

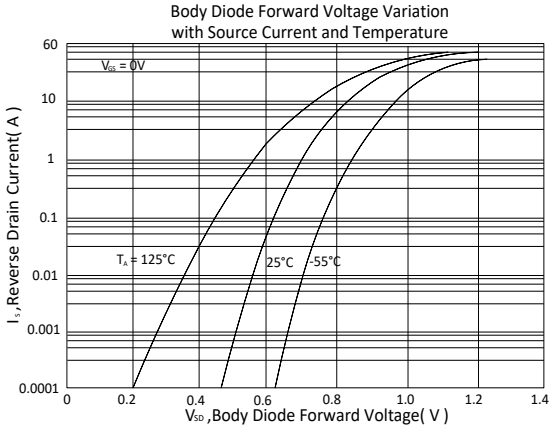


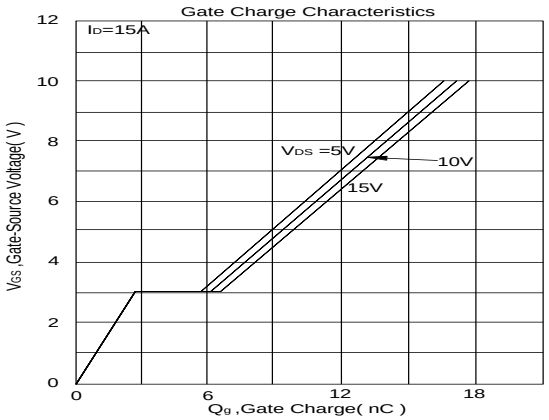


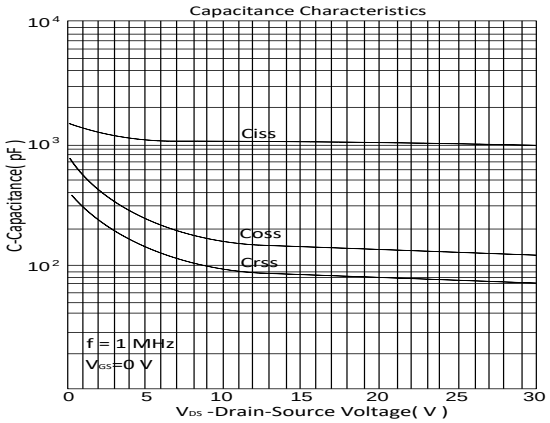


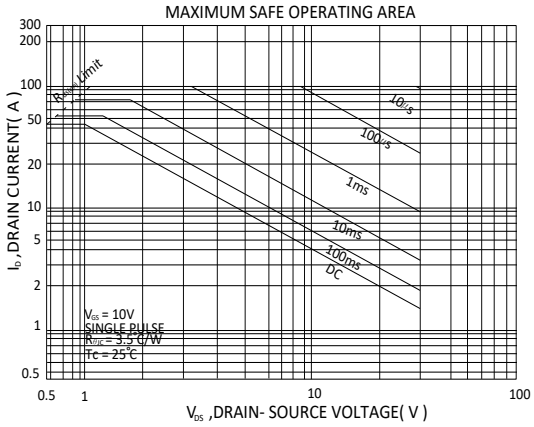


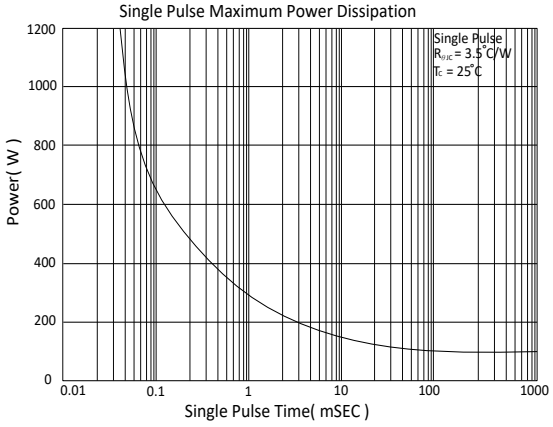


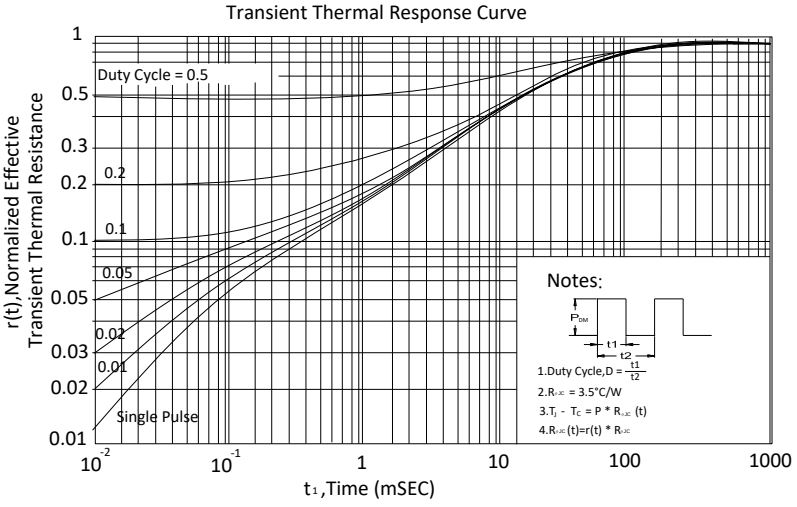



Gate Charge Characteristics
ID=15A
VDS =5V
10V
15V
VGS ,Gate-Source Voltage(V)
Qg ,Gate Charge(nC)

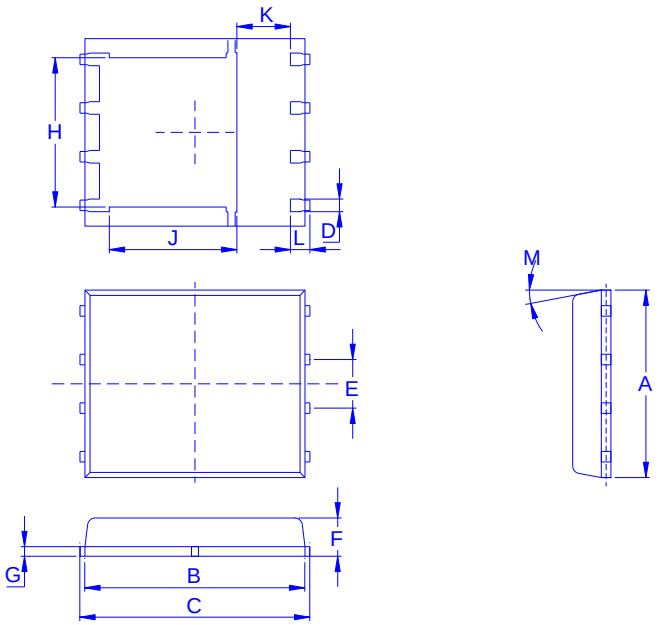

Capacitance Characteristics
Ciss
Coss
Crss
f = 1 MHz
VGS=0 V
C-Capacitance(pF)
VDS -Drain-Source Voltage(V)


MAXIMUM SAFE OPERATING AREA
RDS(on) Limit
10μs
100μs
1ms
10ms
100ms
DC
VGS = 10V
SINGLE PULSE
RθJC = 3.5°C/W
TC = 25°C
ID ,DRAIN CURRENT(A)
VDS ,DRAIN- SOURCE VOLTAGE(V)


Single Pulse Maximum Power Dissipation
Single Pulse
RθJC = 3.5°C/W
TC = 25°C
Power(W)
Single Pulse Time(mSEC)


Transient Thermal Response Curve
Duty Cycle = 0.5
0.2
0.1
0.05
0.02
0.01
Single Pulse
Notes:
1.Duty Cycle,D = t1/t2
2.RθJC = 3.5°C/W
3.TJ - TC = P * RθJC (t)
4.RθJC(t)=r(t) * RθJC
r(t),Normalized Effective Transient Thermal Resistance
t1 ,Time (mSEC)

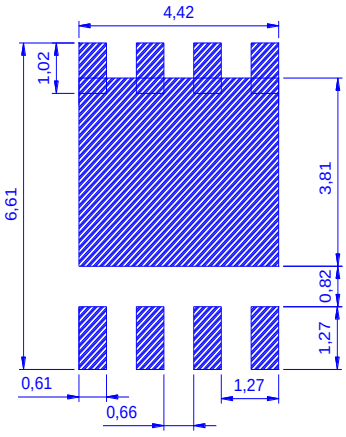
Outline Drawing



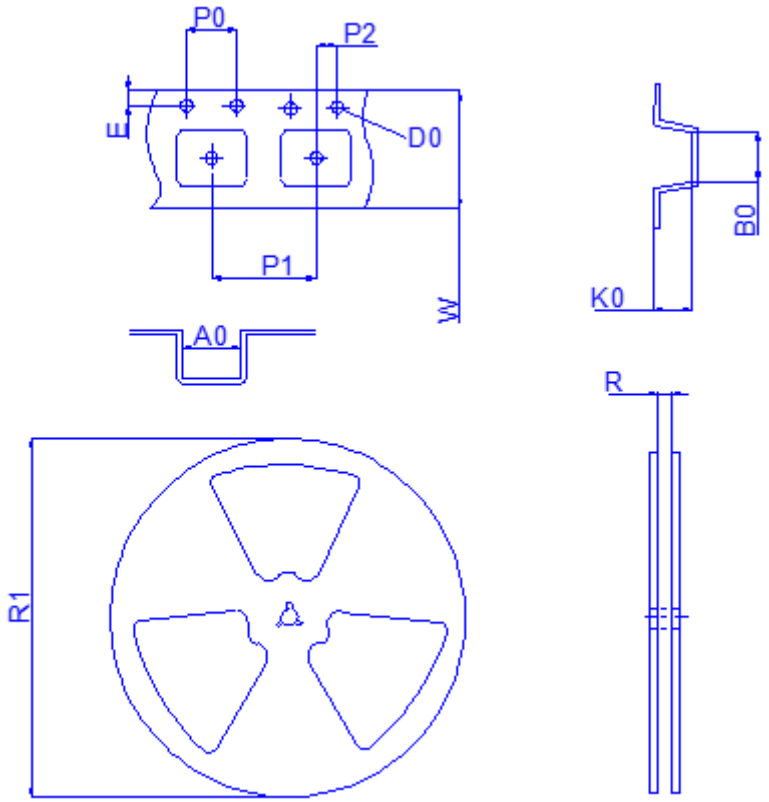
Dimension in mm

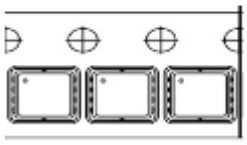
Dimension	A	B	C	D	E	F	G	H	J	K	L	M
Min	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	3.44	1.2	0.4	
Max	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	3.78	1.39	0.71	12°

Recommended minimum pads



Tape&Reel Information:2500pcs/Reel



Package	EDFN5X6
Reel	13"
Device orientation	FEED DIRECTION 

Dimension in mm

Dimension	Carrier tape									Reel	
	A0	B0	D0	E	K0	P0	P1	P2	W	R	R1
Typ.	6.4	5.3	1.5	1.8	1.6	4	8	2	12	12.4	330
±	0.2	0.2	0.1	0.1	0.6	0.1	0.1	0.1	0.3	2	2